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1	Transmittal Letter	09-12-02_IDS_with_foreign_cer_after_Allowance.pdf	58095 aa8e8f2d24f08ea26d9d4125771eb2a6853 c341b	no	2
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2	Information Disclosure Statement (IDS) Filed (SB/08)	09-12-02_Form_PTO_SB08a.pdf	608407 b0eaedc61c55495f8446d1758b4ef7d194 c873d	no	4
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3	NPL Documents	NP01_Japanese_Office_Action _JP2005516103.pdf	214051 5fd066a800c66ca368083e3d1fb5da03a4 35c34	no	5
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4	Fee Worksheet (PTO-875)	fee-info.pdf	30858 76da0ef1ab2e2a1f97c5e7e61af4d61c5955 9b03	no	2
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